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Art Unit: 2827
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VERSIONS WITH MARKING TO SHOW CHANGES MADE

In the Claims

Claims 10-18 were cancelled and claims 19-20 were added. No changes were made to claims 1-9. Added claims 19-20 are provided below:

19. (Added) A sublamination layer, comprising:
 - a single layer etched reference plane having a top surface and a bottom surface, the reference plain being formed by simultaneously etching both sides of a single layer of material;
 - a first signal layer coupled to the top surface with a first bond-ply material;
 - a second signal layer coupled to the bottom surface with a second bond-ply material; and
 - at least one of a through via.
20. (Added) The sublamination layer of claim 19 wherein the reference plane is thicker than either the first signal layer or the second signal layer.